502411194 07/08/2013

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shu-Ting Tsai	07/03/2013
Jeng-Shyan Lin	07/03/2013
Dun-Nian Yaung	07/03/2013
Jen-Cheng Liu	07/03/2013
Feng-Chi Hung	07/03/2013
Chih-Hui Huang	07/03/2013
Sheng-Chau Chen	07/03/2013
Shih Pei Chou	07/03/2013
Chia-Chieh Lin	07/03/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13937055

CORRESPONDENCE DATA

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PATENT

REEL: 030753 FRAME: 0718

OF \$40.00 1393/055

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Address Line 4: Dallas, TEXAS 75219		
ATTORNEY DOCKET NUMBER:	24061.2470	
NAME OF SUBMITTER:	Linda Ingram	
Signature:	/Linda Ingram/	
Date:	07/08/2013	
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PATENT REEL: 030753 FRAME: 0719

Docket No.: 2013-0229/24061.2470

Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1)	Shu-Ting Tsai	of	No. 27, Baoding Street Sanmin District Kaohsiung City 807, Taiwan R.O.C.
(2)	Jeng-Shyan Lin	of	No. 44, Alley 116, Lane 175, Section 1 Datong Road, East District Tainan City 701, Taiwan R.O.C.
(3)	Dun-Nian Yaung	of	4F, No. 15, Lane 130, Wansheng Street Wunshan District Taipei City 116, Taiwan R.O.C.
(4)	Jen-Cheng Liu	of	No. 17, Lane 48, Lane 240, Guo-Seng Street Hsin-Chu City, Taiwan R.O.C.
(5)	Feng-Chi Hung	of	Floor 10, No. 535-2, Bo-Ai Street Chu-Bei City, Hsin-Chu County Taiwan R.O.C.
(6)	Chih-Hui Huang	of	No. 43, Alley 30, Lane 165, Yong-An Road Yongkang City, Tainan County 710 Taiwan R.O.C.
(7)	Sheng-Chau Chen	of	No. 13, Lane 37, Songpu Road Niaosong District Kaohsiung City 833, Taiwan R.O.C.
(8)	Shih Pei Chou	of	No. 6, Alley 26, Lane 167, Tong-An Road Annan District Tainan City 70952, Taiwan R.O.C.
(9)	Chia-Chieh Lin	of	6F, No 79, Haiyang 1st Road Fengshan District Kaohsiung City 830, Taiwan R.O.C.

have invented certain improvements in

INTERCONNECT STRUCTURE FOR STACKED DEVICE

for which we have executed an application for Letters Patent of the United States of America,

of even date filed herewith; and filed on July 8, 2013, and assigned application number 13/937,055; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

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PATENT REEL: 030753 FRAME: 0720

Customer No.: 000042717

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Shu-Ting Tsai		
Residence Address:	No. 27, Baoding Street, Sanmin District Kaohsiung City 807 Taiwan R.O.C.		
Dated: <u>≥0 3.07</u>	. 03 Shu - Ting Tsai Inventor Signature		
Inventor Name:	Jeng-Shyan Lin		
Residence Address:	No. 44, Alley 116, Lane 175, Section 1, Datong Road, East Dist Tainan City 701, Taiwan R.O.C.	rict	
Dated: >013, 4	Jong-Shyah I Inventor Signature	in.	

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Docket No.: 2013-0229/24061.2470

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miventor name:	Dun-Nian Yaung	
Residence Address:	4F, No. 15, Lane 130, Wansher Taipei City 116, Taiwan R.O.C	
Dated: 7/3	13	Inventor Signature
Inventor Name:	Jen-Cheng Liu	0 0
Residence Address:	No. 17, Lane 48, Lane 240, Gu Hsin-Chu City Taiwan R.O.C.	o-Seng Street
Dated: 73 /	3	Jen-Chang Liu Inventor Signature
Inventor Name:	Feng-Chi Hung	777 d.
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Dated: 20 3.	7.3	Fey-Chi Hug Inventor Signature
Inventor Name:	Chih-Hui Huang	
Residence Address:	No. 43, Alley 30, Lane 165, Yo Yongkang City, Tainan County	
Dated: 20/5.7.	. .	Chih-Hui Herang

Jeug - Chau Cheu Inventor Signature

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Sheng-Chau Chen

Inventor Name:

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Docket No.: 2013-0229/24061.2470

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Dated: >013. 7.3.

Inventor Signature

Inventor Name:

Chia-Chieh Lin

Residence Address:

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Kaohsiung City 830, Taiwan R.O.C.

Dated: >0/3.01.03

Inventor Signature

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RECORDED: 07/08/2013

PATENT REEL: 030753 FRAME: 0723